

Frequency Generator & Integrated Buffers for PENTIUM/Pro™

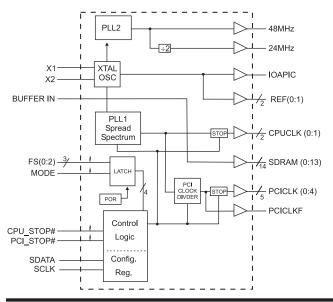
General Description

The ICS9148-26 generates all clocks required for high speed RISC or CISC microprocessor systems such as Intel PentiumPro or Cyrix. Eight different reference frequency multiplying factors are externally selectable with smooth frequency transitions.

Features include two CPU, six PCI and fourteen SDRAM clocks. Two reference outputs are available equal to the crystal frequency. Plus the IOAPIC output powered by VDDL1. One 48 MHz for USB, and one 24 MHz clock for Super IO. Spread Spectrum built in at $\pm 0.5\%$ or $\pm 1.5\%$ modulation to reduce the EMI. Serial programming I 2 C interface allows changing functions, stop clock programing and Frequency selection. Additionally, the device meets the Pentium power-up stabilization, which requires that CPU and PCI clocks be stable within 2ms after power-up. It is not recommended to use I/O dual function pin for the slots (ISA, PIC, CPU, DIMM). The add on card might have a pull up or pull down.

High drive PCICLK and SDRAM outputs typically provide greater than 1 V/ns slew rate into 30pF loads. CPUCLK outputs typically provide better than 1V/ns slew rate into 20pF loads while maintaining $50\pm5\%$ duty cycle. The REF and 24 and 48 MHz clock outputs typically provide better than 0.5 V/ns slew rates into 20pF.

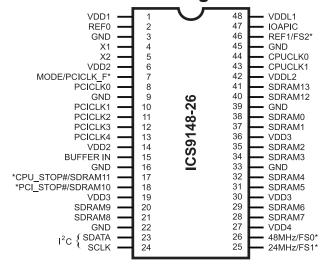
Block Diagram



Features

- 3.3V outputs: SDRAM, PCI, REF, 48/24MHz
- 2.5V outputs: CPU, IOAPIC
- 20 ohm CPU clock output impedance
- 20 ohm PCI clock output impedance
- Skew from CPU (earlier) to PCI clock 1 to 4 ns, center 2.2 ns.
- No external load cap for C_L=18pF crystals
- ±250 ps CPU, PCI clock skew
- 250ps (cycle to cycle) CPU jitter @ 66.66MHz
- Smooth frequency switch, with selections from 50 to 133 MHz CPU.
- I²C interface for programming
- 2ms power up clock stable time
- Clock duty cycle 45-55%.
- 48 pin 300 mil SSOP package
- 3.3V operation, 5V tolerant inputs (with series R)
- <6ns propagation delay SDRAM form Buffer Input</p>

Pin Configuration



48-Pin SSOP

* Internal Pull-up Resistor of 240K to 3.3V on indicated inputs

Power Groups

VDD1 = REF(0:1), X1, X2

VDD2=PCICLK_F, PCICLK(0:4)

VDD3 = SDRAM(0:13), supply for PLL core

VDD4 = 24MHz, 48MHz

VDDL1=IOAPIC

VDDL2=CPUCLK(0:1)

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Pin Descriptions

PIN NUMBER	PIN NAME	TYPE	DESCRIPTION	
1	VDD1	PWR	Ref (0:2), XTAL power supply, nominal 3.3V	
2	REF0	OUT	14.318 Mhz reference clock. This REF output is the STRONGER buffer for ISA BUS loads	
3,9,16,22, 33,39,45	GND	PWR	Ground	
4	X1	IN	Crystal input, has internal load cap (36pF) and feedback resistor from X2	
5	X2	OUT	Crystal output, nominally 14.318MHz. Has internal load cap (36pF)	
6,14	VDD2	PWR	Supply for PCICLK_F and PCICLK (0:5), nominal 3.3V	
	PCICLK_F	OUT	Free running PCI clock	
7	MODE ^{1, 2}	IN	Pin 17, pin 18 function select pin, 1=Desktop Mode, 0=Mobile Mode. Latched Input.	
8	PCICLK0	OUT	PCI clock output.	
10, 11, 12, 13	PCICLK(1:4)	OUT	PCI clock outputs.	
15	BUFFER IN	IN	Input to Fanout Buffers for SDRAM outputs.	
18	PCI_STOP#1	IN	Halts PCICLK(0:4) clocks at logic 0 level, when input low (In mobile mode, MODE=0)	
17, 18, 20, 21, 28, 29, 31, 32, 34, 35,37,38,40,41	SDRAM (0:13)	OUT	(Pins 17, 18 SDRAM output only if MODE=High) SDRAM clock outputs, Fanout Buffer outputs from BUFFER IN pin (controlled by chipset).	
19,30,36	VDD3	PWR	Supply for SDRAM (0:13) and CPU PLL Core, nominal 3.3V.	
23	SDATA	IN	Data input for I ² C serial input, 5V tolerant input	
24	SCLK	IN	Clock input of I ² C input, 5V tolerant input	
25	24MHz	OUT	24MHz output clock	
25	FS1 ^{1, 2}	IN	Frequency select pin. Latched Input.	
26	48MHz	OUT	48MHz output clock	
26	FS0 ^{1, 2}	IN	Frequency select pin. Latched Input	
27	VDD4	PWR	Power for 24 & 48MHz output buffers and fixed PLL core.	
43, 44	CPUCLK(0:1)	OUT	CPU clock outputs, powered by VDDL2. Low if CPU_STOP#=Low	
42	VDDL2	PWR	Supply for CPU (0:1), either 2.5V or 3.3V nominal	
16	REF1	OUT	14.318 MHz reference clock.	
46	FS2 ^{1, 2}	IN	Frequency select pin. Latched Input	
17	CPU_STOP#1	IN	Halts CPUCLK (0:1) clocks at logic 0 level, when input low (in Mobile Mode, MODE=0)	
47	IOAPIC	OUT	IOAPIC clock output. 14.318 MHz Powered by VDDL1.	
48	VDDL1	PWR	Supply for IOAPIC, either 2.5 or 3.3V nominal	

Notes:

- 1: Internal Pull-up Resistor of 240K to 3.3V on indicated inputs
- 2: Bidirectional input/output pins, input logic levels are latched at internal power-on-reset. Use 10Kohm resistor to program logic Hi to VDD or GND for logic low.



Mode Pin - Power Management Input Control

MODE, Pin 7 (Latched Input)	Pin 17	Pin 18
0	CPU_STOP# (INPUT)	PCI_STOP# (INPUT)
1	SDRAM11 (OUTPUT)	SDRAM10 (OUTPUT)

Power Management Functionality

CPU_STOP#	PCI_STOP#	CPUCLK Outputs	PCICLK (0:4)	PCICLK_F, REF, 24/48MHz and SDRAM	Crystal OSC	vco
0	1	Stopped Low	Running	Running	Running	Running
1	1	Running	Running	Running	Running	Running
1	0	Running	Stopped Low	Running	Running	Running
0	0	Stopped Low	Stopped Low	Running	Running	Running

Functionality

 $V_{DD}1,2,3=3.3V\pm5\%,V_{DDL}1,2=2.5V\pm5\%$ or $3.3\pm5\%,$ TA=0 to $70^{\circ}C$ Crystal (X1, X2) = 14.31818MHz

FS2	FS1	FS0	CPU (MHz)	PCICLK (MHz)	REF, IOAPIC (MHz)
1	1	1	100.2	33.3 (CPU/3)	14.318
1	1	0	133.31	33.3 (CPU/4) ¹	14.318
1	0	1	112.01	37.3 (CPU/3) ¹	14.318
1	0	0	103	34.3 (CPU/3)	14.318
0	1	1	66.8	33.4 (CPU/2)	14.318
0	1	0	83.3	41.65 (CPU/2)	14.318
0	0	1	75	37.5 (CPU/2)	14.318
0	0	0	50	25 (CPU/2)	14.318

Note1. Performance not guaranteed



General I²C serial interface information

A. For the clock generator to be addressed by an I²C controller, the following address must be sent as a start sequence, with an acknoledge bit between each byte.

Clock Generator Address (7 bits)		+ 8 bits dummy		+ 8 bits dummy	
A(6:0) & R/W#	ACK	command code	ACK	Byte count	ACK
D2(H)					

Then Byte 0, 1, 2, etc in sequence until STOP.

B. The clock generator is a slave/receiver I²C component. It can read back the data stored in the latches for verification. (set R/W# to 1 above) **Read-Back will support Intel PIIX4 "Block-Read" protocol**, with a "Byte count" following the address with R/W#=1, then proceding to Byte 0, 1, 2, ...until STOP.

Clock Generator Address (7 bits)	A CIV	Byte Count	
A(6:0) & R/W#	ACK	Readback	ACK
D3(H)			

Then Byte 0, 1, 2, etc. in sequence until STOP.

- C. The data transfer rate supported by this clock generator is 100K bits/sec (standard mode)
- D. The input is operating at 3.3V logic levels.
- E. The data byte format is 8 bit bytes.
- F. To simplify the clock generator I²C interface, the protocol is set to use only "Block-Writes" from the controller. The bytes must be accessed in sequential order from lowest to highest byte with the ability to stop after any complete byte has been transferred. The Command code and Byte count shown above must be sent, but the data is ignored for those two bytes. The data is loaded until a Stop sequence is issued.
- G. At power-on, all registers are set to a default condition. Byte 0 defaults to a 0, Bytes 1 through 5 default to a 1 (Enabled output state).

Serial Configuration Command Bitmap

Byte0: Functionality and Frequency Select Register (default = 0)

Bit		Description		PWD		
Bit 7		0 - ±1.5% Spread Spectrum Modulation 1 - ±0.5% Spread Spectrum Modulation				
	Bit6 Bit5 Bit4	CPU clock	PCI			
	111 110	100.2 133.3 ²	33.3 (CPU/3) 33.3 ²			
Bit 6:4	101 100	112.0 ² 103	37.3 ² 34.3 (CPU/3)	Note1		
DII 0.4	011 010	66.8 83.3	33.4 (CPU/2) 41.65(CPU/2)			
	001 000	75 50	37.5 (CPU/2) 25 (CPU/2)			
Bit 3	0 - Frequency is sel 1 - Frequency is sel	elect, Latched Inputs ove)	0			
Bit 2	0 - Spread Spectrum 1 - Spread Spectrum	0				
Bit 1	0 - Normal 1 - Spread Spectrur	0				
Bit 0	0 - Running 1- Tristate all output	s		0		

Note1. Default at Power-up will be for latched logic inputs to define frequency. Bits 4, 5, 6 are default to 000, and if bit 3 is written to a 1 to use Bits 6:4, then these should be defined to desired frequency at same write cycle.

Note2. Performance not guaranteed

Note: PWD = Power-Up Default

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Byte 1: CPU, Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
Bit 7	-	1	(Reserved)
Bit 6	-	1	(Reserved)
Bit 5	-	1	(Reserved)
Bit 4	-	1	(Reserved)
Bit 3	40	1	SDRAM12 (Act/Inact)
Bit 2	41	1	SDRAM13 (Act/Inact)
Bit 1	43	1	CPUCLK1 (Act/Inact)
Bit 0	44	1	CPUCLK0 (Act/Inact)

Notes:

1. Inactive means outputs are held LOW and are disabled from switching.

Byte 2: PCI Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
Bit 7	-	1	(Reserved)
Bit 6	7	1	PCICLK_F (Act/Inact)
Bit 5	-	1	(Reserved)
Bit 4	14	1	PCICLK4 (Act/Inact)
Bit 3	12	1	PCICLK3 (Act/Inact)
Bit 2	11	1	PCICLK2 (Act/Inact)
Bit 1	10	1	PCICLK1 (Act/Inact)
Bit 0	8	1	PCICLK0 (Act/Inact)

Notes:

1. Inactive means outputs are held LOW and are disabled from switching.

Byte 3: SDRAM Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description	
Bit 7	-	1	(Reserved)	
Bit 6	-	1	(Reserved)	
Bit 5	26	1	48MHz (Act/Inact)	
Bit 4	25	1	24 MHz (Act/Inact)	
Bit 3	-	1	(Reserved)	
Bit 2	21,20,18,17	1	SDRAM (8:11) (Active/Inactive) (SDRAM 10, 11 only in Desktop Mode, MODE=1)	
Bit 1	32,31,29,28	1	SDRAM (4:7) (Active/Inactive)	
Bit 0	38,37,35,34	1	SDRAM (0:3) (Active/Inactive)	

Notes:

1. Inactive means outputs are held LOW and are disabled from switching.



Byte 4: Reserved Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
Bit 7	-	1	(Reserved)
Bit 6	-	1	(Reserved)
Bit 5	-	1	(Reserved)
Bit 4	-	1	(Reserved)
Bit 3	-	1	(Reserved)
Bit 2	-	1	(Reserved)
Bit 1	-	1	(Reserved)
Bit 0	-	1	(Reserved)

Notes:

1. Inactive means outputs are held LOW and are disabled from switching.

Byte 5: Peripheral Active/Inactive Register (1 = enable, 0 = disable)

Bit	Pin #	PWD	Description
Bit 7	-	1	(Reserved)
Bit 6	-	1	(Reserved)
Bit 5	-	1	(Reserved)
Bit 4	47	1	IOAPIC0 (Act/Inact)
Bit 3	-	1	(Reserved)
Bit 2	-	1	(Reserved)
Bit 1	46	1	REF1 (Act/Inact)
Bit 0	2	1	REF0 (Act/Inact)

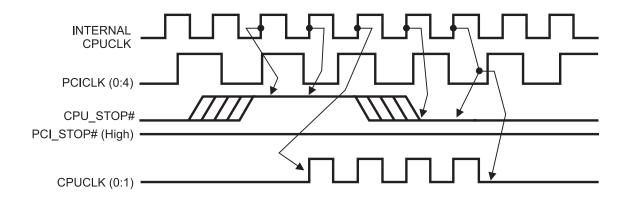
Notes:

1. Inactive means outputs are held LOW and are disabled from switching.



CPU_STOP# Timing Diagram

CPU_STOP# is an asychronous input to the clock synthesizer. It is used to turn off the CPU clocks for low power operation. CPU_STOP# is synchronized by the **ICS9148-26**. The minimum that the CPU clock is enabled (CPU_STOP# high pulse) is 100 CPU clocks. All other clocks will continue to run while the CPU clocks are disabled. The CPU clocks will always be stopped in a low state and start in such a manner that guarantees the high pulse width is a full pulse. CPU clock on latency is less than 4 CPU clocks and CPU clock off latency is less than 4 CPU clocks.



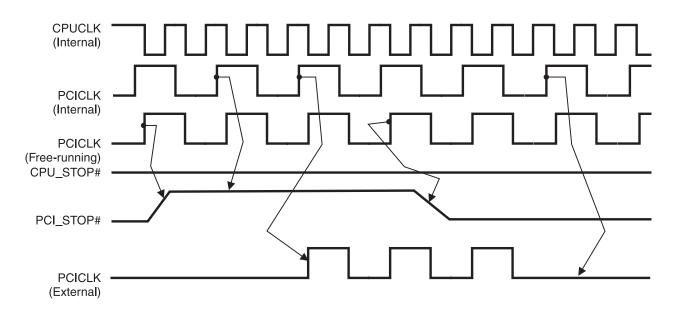
Notes:

- 1. All timing is referenced to the internal CPU clock.
- 2. CPU_STOP# is an asynchronous input and metastable conditions may exist. This signal is synchronized to the CPU clocks inside the ICS9148-26.
- 3. All other clocks continue to run undisturbed.
- 4. SDRAM outputs are controlled by Buffer in signal, not affected by the ICS9148-26 CPU_STOP# signal.



PCI_STOP# Timing Diagram

PCI_STOP# is an asynchronous input to the **ICS9148-26**. It is used to turn off the PCICLK (0:4) clocks for low power operation. PCI_STOP# is synchronized by the **ICS9148-26** internally. The minimum that the PCICLK (0:4) clocks are enabled (PCI_STOP# high pulse) is at least 10 PCICLK (0:4) clocks. PCICLK (0:4) clocks are stopped in a low state and started with a full high pulse width guaranteed. PCICLK (0:4) clock on latency cycles are only one rising PCICLK clock off latency is one PCICLK clock.



Notes:

- 1. All timing is referenced to the Internal CPUCLK (defined as inside the ICS9148 device.)
- 2. PCI_STOP# is an asynchronous input, and metastable conditions may exist. This signal is required to be synchronized inside the ICS9148.
- 3. All other clocks continue to run undisturbed.
- 4. CPU STOP# is shown in a high (true) state.



Shared Pin Operation - Input/Output Pins

Pins 7,25,26,46 on the **ICS9148-26** serve as dual signal functions to the device. During initial power-up, they act as input pins. The logic level (voltage) that is present on these pins at this time is read and stored into a 4-bit internal data latch. At the end of Power-On reset, (see AC characteristics for timing values), the device changes the mode of operations for these pins to an output function. In this mode the pins produce the specified buffered clocks to external loads.

To program (load) the internal configuration register for these pins, a resistor is connected to either the VDD (logic 1) power supply or the GND (logic 0) voltage potential. A 10 Kilohm(10K) resistor is used to provide both the solid CMOS programming voltage needed during the power-up programming period and to provide an insignificant load on the output clock during the subsequent operating period.

Figs. 1 and 2 show the recommended means of implementing this function. In Fig. 1 either one of the resistors is loaded onto the board (selective stuffing) to configure the device's internal logic. Figs. 2a and b provide a single resistor loading option where either solder spot tabs or a physical jumper header may be used.

These figures illustrate the optimal PCB physical layout options. These configuration resistors are of such a large ohmic value that they do not effect the low impedance clock signals. The layouts have been optimized to provide as little impedance transition to the clock signal as possible, as it passes through the programming resistor pad(s).

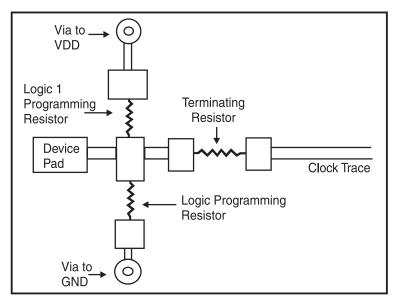


Fig. 1

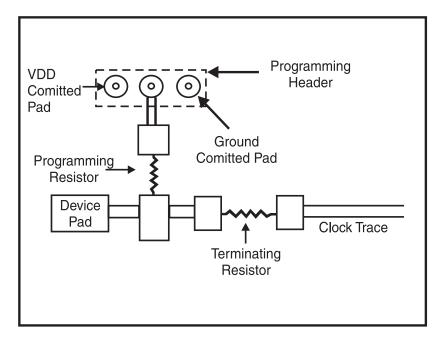


Fig. 2a

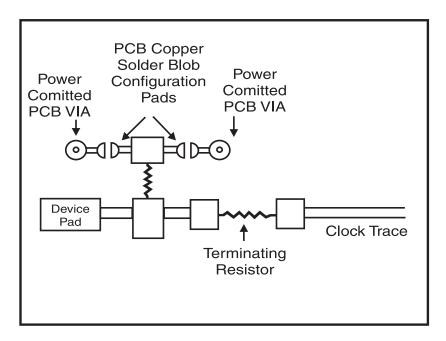


Fig. 2b



Absolute Maximum Ratings

Logic Inputs GND –0.5 V to V_{DD} +0.5 V

Ambient Operating Temperature 0°C to +70°C

Stresses above those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only and functional operation of the device at these or any other conditions above those listed in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Electrical Characteristics - Input/Supply/Common Output Parameters

 $T_A = 0$ - 70C; Supply Voltage $V_{DD} = 3.3 \text{ V} + /-5\%$ (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input High Voltage	V_{IH}		2		V _{DD} +0.3	V
Input Low Voltage	VIL		Vss-0.3		0.8	V
Supply Current	Idd	$C_L = 0 \text{ pF}$; Select @ 66M		77	180	mA
	I_{DDL}			6.0	30	mA
Input frequency	Fi	$V_{DD} = 3.3 \text{ V};$		14.318		MHz
Input Capacitance ¹	Cin	Logic Inputs			5	pF
	CINX	X1 & X2 pins	27	36	45	pS
Transition Time ¹	Ttrans	To 1st crossing of target Freq.		1.5	3	mS
Settling Time ¹	T_s	From 1st crossing to 1% target Freq.				mS
Clk Stabilization 1	T _{STAB}	From $V_{DD} = 3.3 \text{ V}$ to 1% target Freq.			3	mS
Skew ¹	T _{CPU-BUS}	$V_T = 1.5 \text{ V};$	1.0	2.2	4.0	nS

¹Guarenteed by design, not 100% tested in production.



Electrical Characteristics - CPU

 $T_A = 0 - 70C$; $V_{DD} = 3.3 \text{ V} + /-5\%$; $V_{DDL} = 2.5 \text{ V} + /-5\%$; $C_L = 20 \text{ pF}$ (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	R _{DSP2A} ¹	$V_{\rm O} = V_{\rm DD}*(0.5)$	10		20	Ω
Output Impedance	R _{DSN2A} ¹	$V_{\rm O} = V_{\rm DD} * (0.5)$	10		20	Ω
Output High Voltage	V _{OH2B}	$I_{OH} = -12.0 \text{ mA}$	2	2.3		V
Output Low Voltage	V _{OL2B}	$I_{OL} = 12 \text{ mA}$		0.2	0.4	V
Output High Current	Іон2в	Vон = 1.7 V		-41	-19	mA
Output Low Current	I _{OL2B}	$V_{OL} = 0.7 \text{ V}$	19	37		mA
Rise Time	t_{r2A}^{1}	$V_{OL} = 0.4 \text{ V}, V_{OH} = 2.0 \text{ V}$		1.3	2.1	nS
Fall Time	t _{f2} A ¹	$V_{OH} = 2.0 \text{ V}, V_{OL} = 0.4 \text{ V}$		1.0	2.0	nS
Duty Cycle	d_{t2A}^{1}	$V_T = 1.25 \text{ V}$	45.0	51.0	55.0	%
Skew (Window)	tsk2A	$V_T = 1.25 \text{ V}$		120	250	pS
	period(norm)	$V_T = 1.25 \text{ V}; 100 \text{MHz}$	9.75	10	10.25	nS
	period(spr)	$V_T = 1.25 \text{ V}; 100 \text{MHz}$	9.75	10	10.35	nS
Jitter	tj1s2A	$V_T = 1.25 \text{ V}$		120	350	pS
	tjabs2A	$V_T = 1.25 \text{ V}$	-250	100	+250	
	Dev run avg	$V_T = 1.25 \text{ V}$		150	250	pS

Guarenteed by design, not 100% tested in production.



Electrical Characteristics - 24M, 48M, REF 1

 $T_A = 0 - 70C$; $V_{DD} = V_{DDL} = 3.3 \text{ V} + /-5\%$; $C_L = 20 \text{ pF}$ (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	R _{DSP5} ¹	$V_{\rm O} = V_{\rm DD}*(0.5)$		20	60	W
Output Impedance	R _{DSN5} ¹	$V_{\rm O} = V_{\rm DD}*(0.5)$		55	100	W
Output High Voltage	V _{OH5}	$I_{OH} = -14 \text{ mA}$	2.4	2.9		V
Output Low Voltage	V _{OL5}	$I_{OL} = 6.0 \text{ mA}$		0.25	0.4	V
Output High Current	I _{OH5}	$V_{OH} = 2.0 \text{ V}$		-42	-20	mA
Output Low Current	I _{OL5}	$V_{OL} = 0.8 \text{ V}$	10	18		mA
Rise Time	t_{r5}^{1}	$V_{OL} = 0.8 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.1	2.0	nS
Fall Time	$t_{\mathfrak{S}}^{1}$	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.8 \text{ V}$		1.0	2.5	nS
Duty Cycle	d_{t5}^{1}	$V_T = 1.5 \text{ V}$	40.0	52.0	60.0	%
Jitter	t _{j1s5} 1	$V_T = 1.5 \text{ V}$		100	250	pS
	tjabs5	$V_T = 1.5 \text{ V}$		250	800	pS

¹Guarenteed by design, not 100% tested in production.



Electrical Characteristics - BUS

 $T_A = 0 - 70C$; $V_{DD} = 3.3 \text{ V} + /-5\%$; $C_L = 30 \text{ pF}$ (unless otherwise stated)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	R_{DSP1}^{1}	$V_{\rm O} = V_{\rm DD}*(0.5)$	12	23	55	Ω
Output Impedance	Rdsn1	$V_{\rm O} = V_{\rm DD}*(0.5)$	12	20	55	Ω
Output High Voltage	Voh1	Іон = -18 mA	2.4	2.9		V
Output Low Voltage	V_{OL1}	$I_{OL} = 9.4 \text{ mA}$		0.2	0.4	V
Output High Current	Іон1	$V_{OH} = 2.0 \text{ V}$		-58	-22	mA
Output Low Current	Iol1	$V_{OL} = 0.8 \text{ V}$	25	52		mA
Rise Time	t_{r1}^{-1}	$V_{OL} = 0.8 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.5	2.0	nS
Fall Time	tfl 1	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.8 \text{ V}$		1.4	2.5	nS
Duty Cycle	d_{t1}^{1}	$V_T = 1.5 \text{ V}$	45.0	50.0	55.0	%
Skew	tsk1	$V_T = 1.5 \text{ V}$		80	250	pS
Jitter	tj1s1	$V_T = 1.5 \text{ V}$		50	150	pS
	tjabs 1	$V_T = 1.5 \text{ V}$		200	500	pS

Guarenteed by design, not 100% tested in production.



Electrical Characteristics - SDRAM

 $T_A = 0 - 70C$; $V_{DD} = V_{DDL} 3.3 \text{ V} + /-5\%$; $C_L = 30 \text{ pF} \text{ (unless otherwise stated)}$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Output Impedance	R_{DSP2A}^{1}	$V_O = V_{DD}*(0.5)$	10		20	Ω
Output Impedance	Rdsn2a ¹	$V_O = V_{DD}*(0.5)$	10		20	Ω
Output High Voltage	V _{OH2} A	$I_{OH} = -28 \text{ mA}$	2.4	2.8		V
Output Low Voltage	V _{OL2A}	$I_{OL} = 19 \text{ mA}$		0.3	0.4	V
Output High Current	I _{OH2} A	$V_{OH} = 2.0 \text{ V}$		-72	-42	mA
Output Low Current	Iol2a	$V_{OL} = 0.8 \text{ V}$	33	50		mA
Rise Time	t_{r2A}^{1}	$V_{OL} = 0.8 \text{ V}, V_{OH} = 2.4 \text{ V}$		1.1	2.0	nS
Fall Time	t _{f2} A ¹	$V_{OH} = 2.4 \text{ V}, V_{OL} = 0.8 \text{ V}$		1.5	2.5	nS
Duty Cycle	d_{t2A}^{1}	$V_T = 1.5 \text{ V}$	55	65	75	%
Skew (output to output)	tsk2A	$V_T = 1.5 \text{ V}$		200	600	pS
Skew (Bufferin to output)	t_{sk2A}^{1}	$V_T = 1.5 \text{ V}$		5.5	7.0	nS

¹Guarenteed by design, not 100% tested in production.

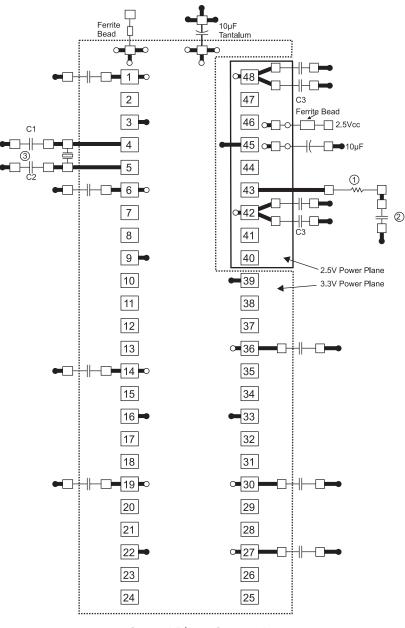
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General Layout Precautions:

- 1) Use a ground plane on the top layer of the PCB in all areas not used by traces.
- 2) Make all power traces and vias as wide as possible to lower inductance.

Notes:

- 1 All clock outputs should have series terminating resistor. Not shown in all places to improve readibility of diagram
- 2 Optional EMI capacitor should be used on all CPU, SDRAM, and PCI outputs.
- 3 Optional crystal load capacitors are recommended.



Capacitor Values:

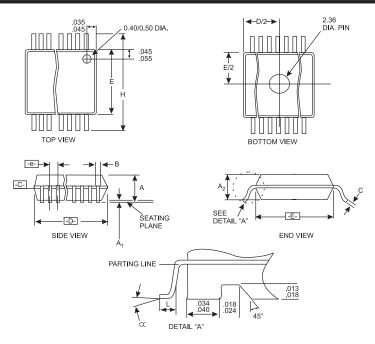
C1, C2: Crystal load values determined by user

C3:100pF ceramic

All unmarked capacitors are 0.01 µF ceramic

- = Ground Plane Connection
- = Power Plane Conncetion
- □ = Solder Pads





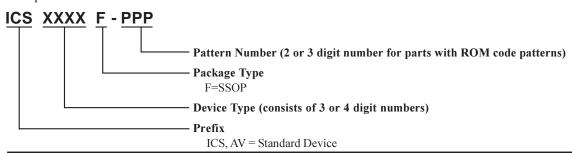
SSOP Package

SYMBOL	CO	MMON DIME	ENSIONS	VARIATIONS	D			N
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
A	.095	.101	.110	AC	.620	.625	.630	48
A 1	.008	.012	.016					
A 2	.088	.090	.092					
В	.008	.010	.0135					
С	.005	-	.010					
D		See Variatio	ns					
E	.292	.296	.299					
e		0.025 BSC						
Н	.400	.406	.410	1				
h	.010	.013	.016					
L	.024	.032	.040					
N		See Variatio	ns					
∞	0°	5°	8°					
X	.085	.093	.100					

Ordering Information

ICS9148F-26

Example:



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